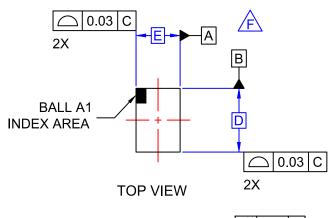
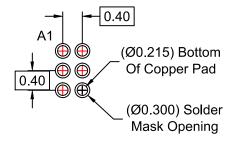
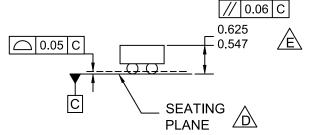
WLCSP6 1.38x0.94x0.625 CASE 567UH ISSUE O

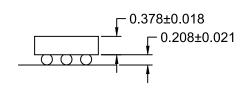
DATE 31 APR 2017





RECOMMENDED LAND PATTERN (NSMD PAD TYPE)





SIDE VIEWS

NOTES

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER $_{\wedge}$ ASME Y14.5M, 2009.
- D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
 - E. PACKAGE NOMINAL HEIGHT IS

586 ± 39 MICRONS (547-625 MICRONS).

FOR DIMENSIONS D,E,X, AND Y SEE PRODUCT DATASHEET.

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DESCRIPTION:	WLCSP6 1.38x0.94x0.625		PAGE 1 OF 1

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